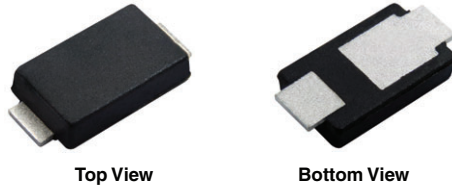


# Surface-Mount TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifier

## eSMP<sup>®</sup> Series



Top View

Bottom View

### SMPA (DO-221BC)

Anode Cathode

## LINKS TO ADDITIONAL RESOURCES


[3D Models](#)

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	8.0 A
$V_{RRM}$	100 V
$I_{FSM}$	90 A
$V_F$ at $I_F = 8.0$ A ( $T_J = 125$ °C)	0.63 V
$T_J$ max.	175 °C
Package	SMPA (DO-221BC)
Circuit configuration	Single

## FEATURES

- Very low profile - typical height of 0.95 mm
- Ideal for automated placement
- Trench MOS Schottky technology
- Low power losses, high efficiency
- Low forward voltage drop
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
  - Automotive ordering code: P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
 COMPLIANT  
 HALOGEN  
**FREE**

## TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial and automotive applications.

## MECHANICAL DATA

### Case: SMPA (DO-221BC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

**Polarity:** color band denotes cathode end

MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)			
PARAMETER	SYMBOL	V8PAM10S	UNIT
Device marking code		8MBS	
Maximum repetitive peak reverse voltage	$V_{RRM}$	100	V
Maximum DC forward current	$I_{F(AV)}$ <sup>(1)</sup>	8.0	A
	$I_{F(AV)}$ <sup>(2)</sup>	2.8	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	90	A
Operating junction temperature range	$T_J$ <sup>(3)</sup>	-40 to +175	°C
Storage temperature range	$T_{STG}$	-55 to +175	°C

## Notes

(1) Units mounted on 3 cm x 3 cm aluminum PCB

(2) Free air, mounted on recommended copper pad area, 2 oz., FR4 PCB

(3) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$



ELECTRICAL CHARACTERISTICS (T <sub>J</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 4.0 A	T <sub>J</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.61	-	V
	I <sub>F</sub> = 8.0 A			0.75	0.84	
	I <sub>F</sub> = 4.0 A	T <sub>J</sub> = 125 °C		0.53	-	
	I <sub>F</sub> = 8.0 A			0.63	0.71	
Reverse current	V <sub>R</sub> = 70 V	T <sub>J</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	0.003	-	mA
		T <sub>J</sub> = 125 °C		1.5	-	
	V <sub>R</sub> = 100 V	T <sub>J</sub> = 25 °C		-	0.18	
		T <sub>J</sub> = 125 °C		3	9	
Typical junction capacitance	4.0 V, 1 MHz		C <sub>J</sub>	600	-	pF

**Notes**

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
- (2) Pulse test: Pulse width ≤ 5 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise specified)			
PARAMETER	SYMBOL	V8PAM10S	UNIT
Typical thermal resistance	R <sub>θJA</sub> <sup>(1)(2)</sup>	100	°C/W
	R <sub>θJM</sub> <sup>(3)</sup>	5	

**Notes**

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: dP<sub>D</sub>/dT<sub>J</sub> < 1/R<sub>θJA</sub>
- (2) Free air, mounted on recommended PCB, 2 oz. pad area; thermal resistance R<sub>θJA</sub> - junction to ambient
- (3) Units mounted on 3 cm x 3 cm aluminum PCB; thermal resistance R<sub>θJM</sub> - junction to mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V8PAM10S-M3/H	0.032	H	3500	7" diameter plastic tape and reel
V8PAM10S-M3/I	0.032	I	14 000	13" diameter plastic tape and reel
V8PAM10SHM3/H <sup>(1)</sup>	0.032	H	3500	7" diameter plastic tape and reel
V8PAM10SHM3/I <sup>(1)</sup>	0.032	I	14 000	13" diameter plastic tape and reel

**Note**

- (1) AEC-Q101 qualified

**RATINGS AND CHARACTERISTICS CURVES (T<sub>A</sub> = 25 °C unless otherwise specified)**

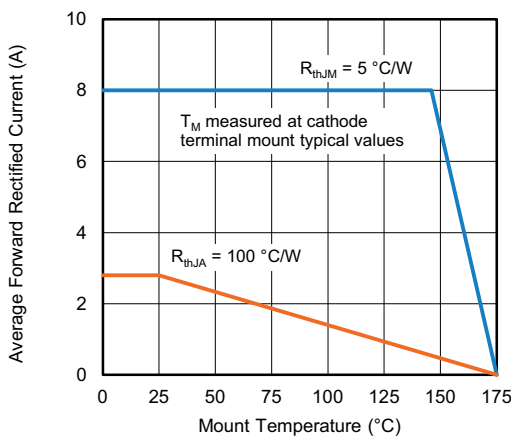


Fig. 1 - Maximum Forward Current Derating Curve

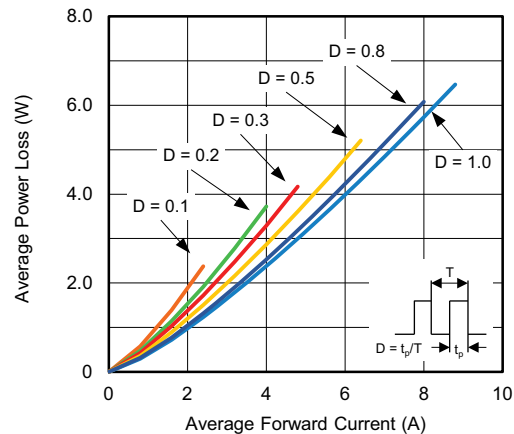


Fig. 2 - Forward Power Loss Characteristics

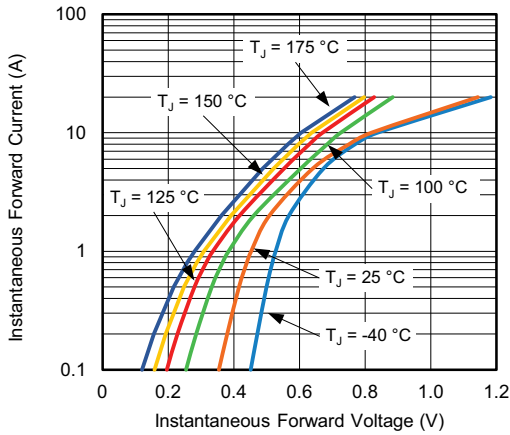


Fig. 3 - Typical Instantaneous Forward Characteristics

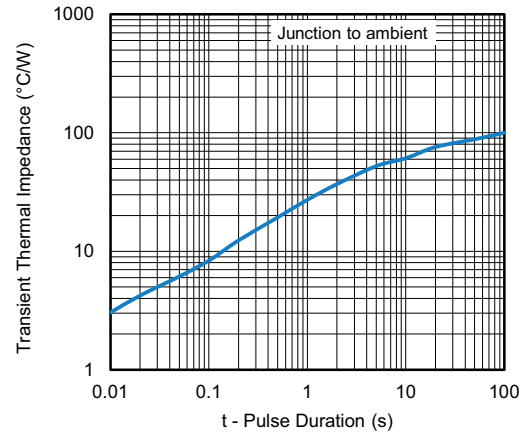


Fig. 6 - Typical Transient Thermal Impedance

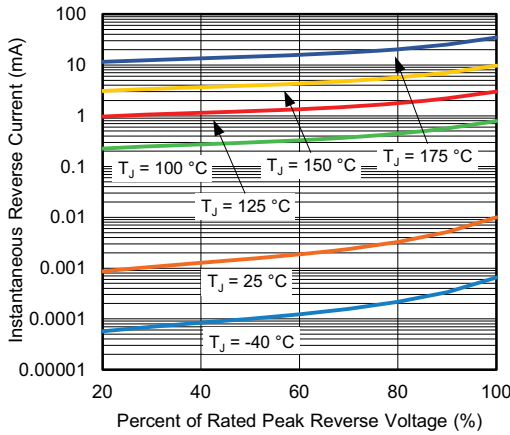


Fig. 4 - Typical Reverse Leakage Characteristics

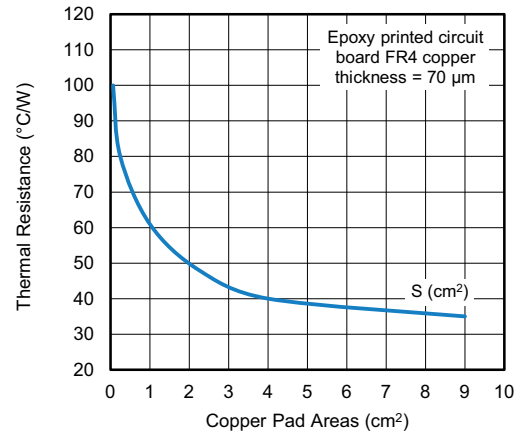


Fig. 7 - Thermal Resistance Junction to Ambient vs. Copper Pad Areas

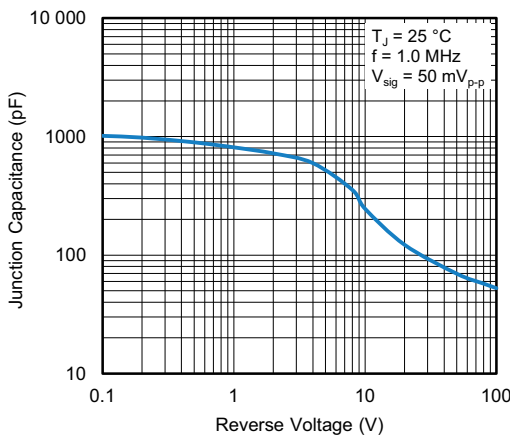
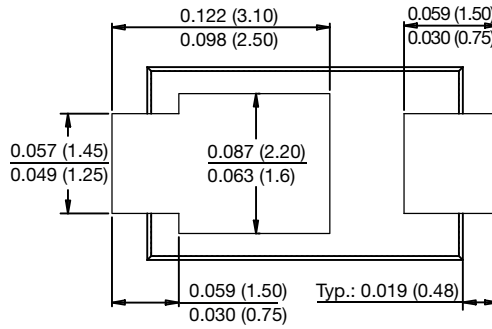
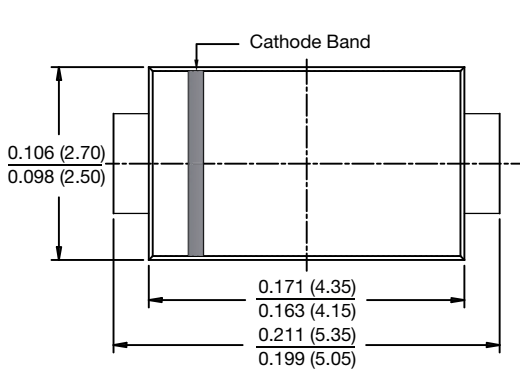


Fig. 5 - Typical Junction Capacitance

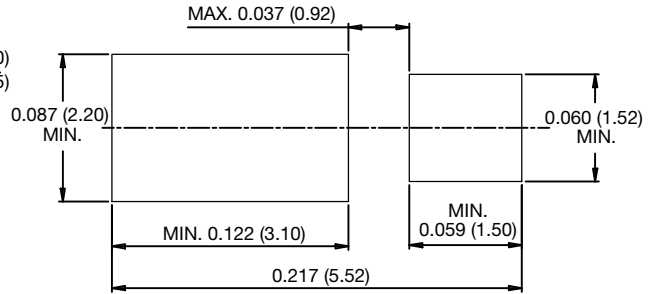
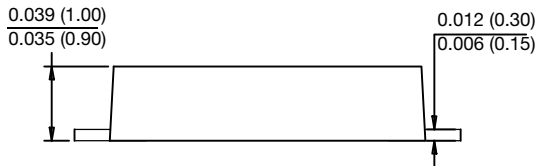


### PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

#### SMPS (DO-221BC)



#### Mounting Pad Layout





## Disclaimer

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